# 12-Stage Binary Ripple Counter

### **High-Performance Silicon-Gate CMOS**

The MC74C4040A is identical in pinout to the standard CMOS MC14040. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device consists of 12 master-slave flip-flops. The output of each flip-flop feeds the next and the frequency at each output is half of that of the preceding one. The state counter advances on the negative-going edge of the Clock input. Reset is asynchronous and active-high.

State changes of the Q outputs do not occur simultaneously because of internal ripple delays. Therefore, decoded output signals are subject to decoding spikes and may have to be gated with the Clock of the HC4040A for some designs.

#### **Features**

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance With JEDEC Standard No. 7A Requirements
- Chip Complexity: 398 FETs or 99.5 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

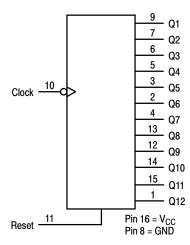


Figure 1. Logic Diagram



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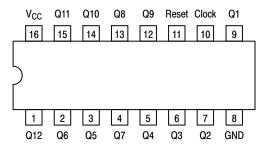
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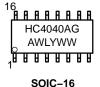
SOIC-16 D SUFFIX CASE 751B TSSOP-16 DT SUFFIX CASE 948F

#### **PIN ASSIGNMENT**



16-Lead Package (Top View)

## MARKING DIAGRAMS





A = Assembly Location

L, WL = Wafer Lot Y, YY = Year W, WW = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **FUNCTION TABLE**

Clock	Reset	Output State
	L	No Charge
	L	Advance to Next State
Х	Н	All Outputs Are Low

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>in</sub>	DC Input Voltage (Referenced to GND)	$-0.5$ to $V_{CC} + 0.5$	V
V <sub>out</sub>	DC Output Voltage (Referenced to GND)	$-0.5$ to $V_{CC}$ + 0.5	V
l <sub>in</sub>	DC Input Current, per Pin	±20	mA
l <sub>out</sub>	DC Output Current, per Pin	±25	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA
$P_{D}$	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds SOIC or TSSOP Package	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range GND  $\leq$  ( $V_{in}$  or  $V_{out}$ )  $\leq$   $V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{\rm CC}$ ). Unused outputs must be left open.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

†Derating: SOIC Package: –7 mW/°C from 65° to 125°C TSSOP Package: –6.1 mW/°C from 65° to 125°C

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature Range, All Package Types	<b>-</b> 55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $V_{CC} = 2.0 \text{ V}$		1000	ns
	(Figure 2) $V_{CC} = 3.0 \text{ V}$	0	600	
	$V_{CC} = 4.5  \text{V}$	0	500	
	$V_{CC} = 6.0 V_{CC}$	0	400	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### DC CHARACTERISTICS (Voltages Referenced to GND)

				v <sub>cc</sub>	Guara	nteed Lin	nit	
Symbol	Parameter	Condit	ion	V	–55 to 25°C	≤85°C	≤125°C	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage	$V_{out} = 0.1V \text{ or } V_{CC}$ $ I_{out}  \le 20 \mu A$	-0.1V	2.0 3.0 4.5 6.0	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	$V_{out} = 0.1 V \text{ or } V_{CC} \cdot  I_{out}  \le 20 \mu A$	– 0.1V	2.0 3.0 4.5 6.0	0.50 0.90 1.35 1.80	0.50 0.90 1.35 1.80	0.50 0.90 1.35 1.80	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20 \mu A$		2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{in} = V_{IH}$ or $V_{IL}$	$\begin{aligned}  I_{out}  &\leq 2.4 \text{mA} \\  I_{out}  &\leq 4.0 \text{mA} \\  I_{out}  &\leq 5.2 \text{mA} \end{aligned}$	3.0 4.5 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.20 3.70 5.20	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20 \mu A$		2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{in} = V_{IH}$ or $V_{IL}$	$\begin{aligned}  I_{out}  &\leq 2.4 \text{mA} \\  I_{out}  &\leq 4.0 \text{mA} \\  I_{out}  &\leq 5.2 \text{mA} \end{aligned}$	3.0 4.5 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.40 0.40 0.40	
l <sub>in</sub>	Maximum Input Leakage Current	$V_{in} = V_{CC}$ or GND		6.0	±0.1	±1.0	±1.0	μΑ
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0\mu A$		6.0	4	40	160	μΑ

#### **AC CHARACTERISTICS** ( $C_L = 50 \text{ pF}$ , Input $t_r = t_f = 6 \text{ ns}$ )

		V <sub>CC</sub>	Guaranteed Limit			
Symbol	Parameter		-55 to 25°C	≤ <b>85</b> °C	≤125°C	Unit
f <sub>max</sub>	Maximum Clock Frequency (50% Duty Cycle) (Figures 2 and 5)	2.0 3.0 4.5 6.0	10 15 30 50	9.0 14 28 45	8.0 12 25 40	MHz
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Clock to Q1* (Figures 2 and 5)	2.0 3.0 4.5 6.0	96 63 31 25	106 71 36 30	115 88 40 35	ns
t <sub>PHL</sub>	Maximum Propagation Delay, Reset to Any Q (Figures 3 and 5)	2.0 3.0 4.5 6.0	65 30 30 26	72 36 35 32	90 40 40 35	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Qn to Qn+1 (Figures 4 and 5)	2.0 3.0 4.5 6.0	69 40 17 14	80 45 21 15	90 50 28 22	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 2 and 5)	2.0 3.0 4.5 6.0	75 27 15 13	95 32 19 15	110 36 22 19	ns
C <sub>in</sub>	Maximum Input Capacitance	•	10	10	10	pF

<sup>\*</sup> For  $T_A = 25^{\circ}C$  and  $C_L = 50$  pF, typical propagation delay from Clock to other Q outputs may be calculated with the following equations:  $V_{CC} = 2.0 \text{ V}$ :  $t_P = [93.7 + 59.3 \text{ (n-1)}] \text{ ns}$   $V_{CC} = 4.5 \text{ V}$ :  $t_P = [30.25 + 14.6 \text{ (n-1)}] \text{ ns}$ 

 $V_{CC} = 3.0 \text{ V: } t_P = [61.5 + 34.4 (n-1)] \text{ ns}$ 

 $V_{CC} = 4.3 \text{ V. tp} = [30.23 + 14.0 \text{ (n-1)}]$  $V_{CC} = 6.0 \text{V: tp} = [24.4 + 12 \text{ (n-1)}] \text{ ns}$ 

рF

		Typical @ $25^{\circ}$ C, $V_{CC} = 5.0 \text{ V}$
$C_{PD}$	Power Dissipation Capacitance (Per Package)*	31

<sup>\*</sup>Used to determine the no-load dynamic power consumption: P<sub>D</sub> = C<sub>PD</sub> V<sub>CC</sub><sup>2</sup>f + I<sub>CC</sub> V<sub>CC</sub>.

#### **TIMING REQUIREMENTS** (Input $t_r = t_f = 6 \text{ ns}$ )

		V <sub>CC</sub>	Guaranteed Limit			
Symbol	Parameter	v	-55 to 25°C	≤85°C	≤125°C	Unit
t <sub>rec</sub>	Minimum Recovery Time, Reset Inactive to Clock	2.0	30	40	50	ns
	(Figure 3)	3.0	20	25	30	
		4.5	5	8	12	
		6.0	4	6	9	
t <sub>w</sub>	Minimum Pulse Width, Clock	2.0	70	80	90	ns
	(Figure 2)	3.0	40	45	50	
		4.5	15	19	24	
		6.0	13	16	20	
t <sub>w</sub>	Minimum Pulse Width, Reset	2.0	70	80	90	ns
	(Figure 3)	3.0	40	45	50	
		4.5	15	19	24	
		6.0	13	16	20	
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times	2.0	1000	1000	1000	ns
	(Figure 2)	3.0	800	800	800	
		4.5	500	500	500	
		6.0	400	400	400	

#### **PIN DESCRIPTIONS**

#### **INPUTS**

#### Clock (Pin 10)

Negative-edge triggering clock input. A high-to-low transition on this input advances the state of the counter.

#### Reset (Pin 11)

Active-high reset. A high level applied to this input asynchronously resets the counter to its zero state, thus forcing all Q outputs low.

#### **OUTPUTS**

Q1 thru Q12 (Pins 9, 7, 6, 5, 3, 2, 4, 13, 12, 14, 15, 1)

Active-high outputs. Each Qn output divides the Clock input frequency by  $2^N$ .

#### **SWITCHING WAVEFORMS**

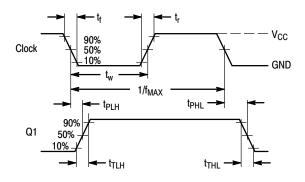


Figure 2.

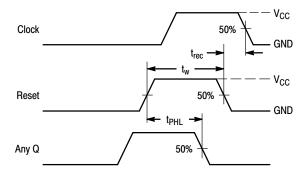


Figure 3.

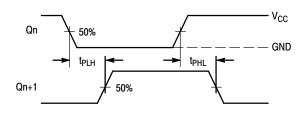
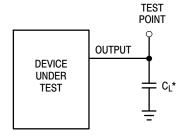


Figure 4.



\*Includes all probe and jig capacitance

Figure 5. Test Circuit

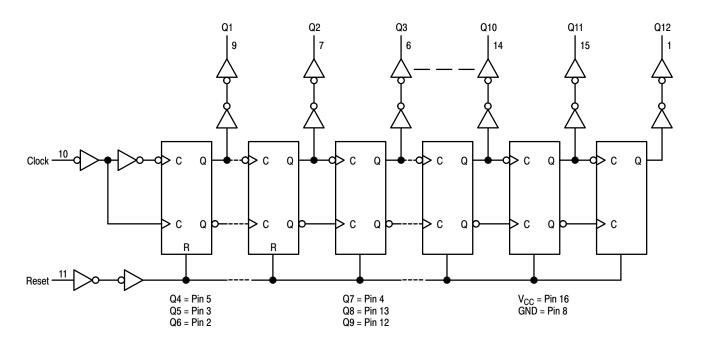


Figure 6. Expanded Logic Diagram

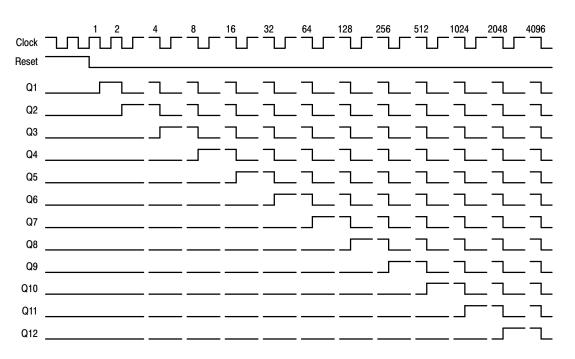


Figure 7. Timing Diagram

#### **APPLICATIONS INFORMATION**

#### Time-Base Generator

A 60Hz sinewave obtained through a 100 K resistor connected to a 120 Vac power line through a step down transformer is applied to the input of the MC54/74HC14A, Schmitt-trigger inverter. The HC14A squares—up the input

waveform and feeds the HC4040A. Selecting outputs Q5, Q10, Q11, and Q12 causes a reset every 3600 clocks. The HC20 decodes the counter outputs, produces a single (narrow) output pulse, and resets the binary counter. The resulting output frequency is 1.0 pulse/minute.

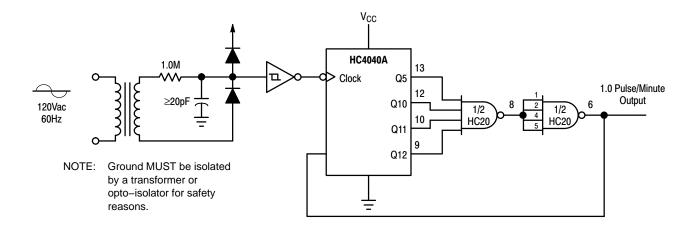


Figure 8. Time-Base Generator

#### **ORDERING INFORMATION**

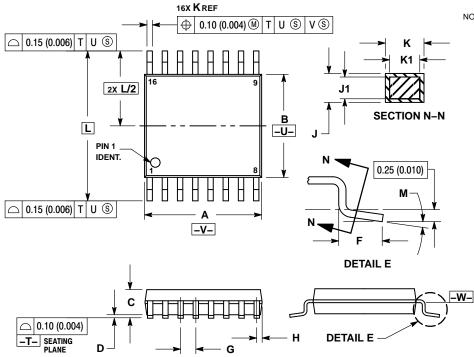
Device	Package	Shipping <sup>†</sup>
MC74HC4040ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC4040ADR2G	SOIC-16 (Pb-Free)	2500 Units / Reel
NLV74HC4040ADR2G*	SOIC-16 (Pb-Free)	2500 Units / Reel
MC74HC4040ADTR2G	TSSOP-16 (Pb-Free)	2500 Units / Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

#### PACKAGE DIMENSIONS

#### TSSOP-16 CASE 948F **ISSUE B**



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS.
  - FLASH. PROVINCISIONS OR GATE BURRS.
    MOLD FLASH OR GATE BURRS SHALL NOT
    EXCEED 0.15 (0.006) PER SIDE.
    4. DIMENSION B DOES NOT INCLUDE
    INTERLEAD FLASH OR PROTRUSION.
    INTERLEAD FLASH OR PROTRUSION SHALL
    NOT EXCEED 0.01 (0.001) PER DIST.
  - NOT EXCEED 0.25 (0.010) PER SIDE.

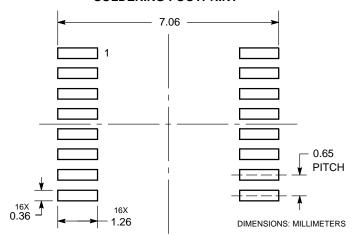
    5. DIMENSION K DOES NOT INCLUDE
    DAMBAR PROTRUSION. ALLOWABLE
    DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
    6. TERMINAL NUMBERS ARE SHOWN FOR

  - REFERENCE ONLY.

    7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W-.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	0.65 BSC		BSC	
Н	0.18	0.28	0.007	0.011	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252 BSC		
M	0°	8°	0°	8°	

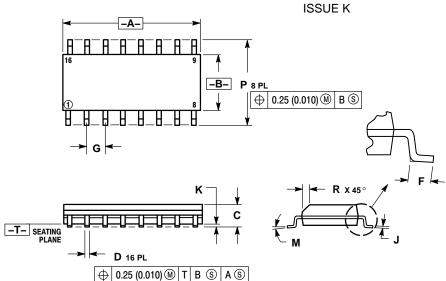
#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

#### SOIC-16 CASE 751B-05



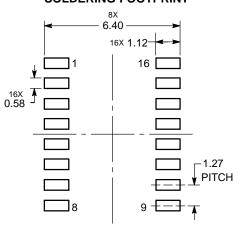
#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- PHOI HUSION.

  MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR PROTRUSION
  SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D
  DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
C	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050	0 BSC	
7	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

#### **SOLDERING FOOTPRINT\***



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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